



MULTI-INNO TECHNOLOGY CO., LTD.

# LCD MODULE SPECIFICATION

**Model : MI0800ET**

Revision	
Engineering	
Date	
Our Reference	



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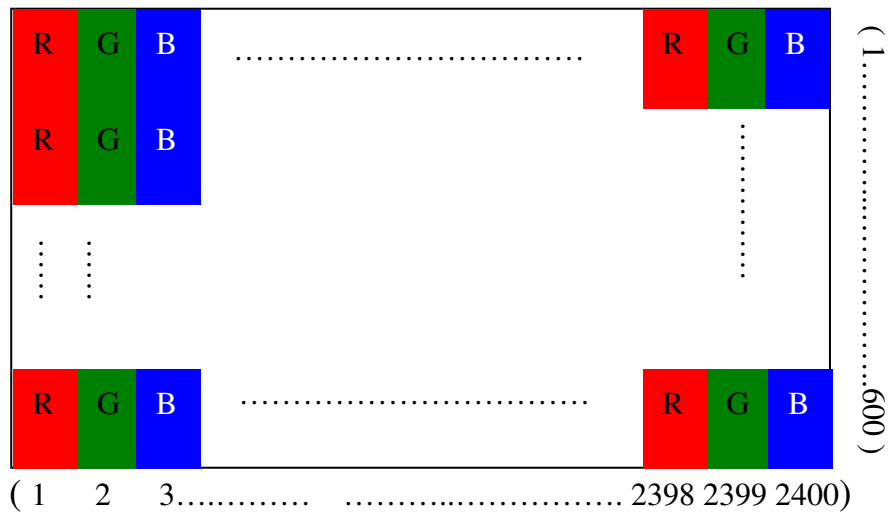
**Appendix:**

Fig.1-(a) Outline dimension of TFT-LCD module(Front side)..... **P20**  
Fig.1-(b) Outline dimension of TFT-LCD module(Back side)..... **P21**

### A. Physical specifications

NO.	Item	Specification	Remark
1	Display resolution (dot)	800RGB(W)x600(H)	
2	Active area (mm)	162(W)x121.5(H)	
3	Dot pitch (mm)	0.2025(W)x0.2025(H)	
4	Color configuration	R. G. B. stripe	Note 1
5	Overall dimension (mm)	183(W)x141(H)x6.3(D)	Note 2
6	Weight (g)	235 ±10	
7	Surface treatment	Anti-Glare	
8	Backlight unit	24 pcs of LED	

Note 1: Below figure shows the dot stripe arrangement.



Note 2: Refer to Fig. 1

## B. Electrical specifications

### 1. Pin assignment

#### a. TFT-LCD panel driving section

Pin no	Symbol	I/O	Description	Remark
1	AGND2	P	Analog Ground	
2	AVDD2	P	Analog Power	
3	VDD	P	Digital Power	
4	R0	I	Data input (LSB)	
5	R1	I	Data input	
6	R2	I	Data input	
7	R3	I	Data input	
8	R4	I	Data input	
9	R5	I	Data input	
10	R6	I	Data input	
11	R7	I	Data input (MSB)	
12	G0	I	Data input (LSB)	
13	G1	I	Data input	
14	G2	I	Data input	
15	G3	I	Data input	
16	G4	I	Data input	
17	G5	I	Data input	
18	G6	I	Data input	
19	G7	I	Data input (MSB)	
20	B0	I	Data input (LSB)	
21	B1	I	Data input	
22	B2	I	Data input	
23	B3	I	Data input	
24	B4	I	Data input	
25	B5	I	Data input	
26	B6	I	Data input	
27	B7	I	Data input (MSB)	
28	DCLK	I	Clock input	
29	DE	I	Data enable signal	
30	HSYNC	I	Horizontal sync input. Negative polarity	
31	VSYNC	I	Vertical sync input. Negative polarity	
32	SCL	I	Serial communication clock input	
33	SDA	I	Serial communication data input	
34	CSB	I	Serial communication chip select	
35	FBA	I	DCDC feed back signal	

36	VDD	P	Digital Power	
37	DRVA	O	DCDC PWM signal	
38	GND	P	Digital ground	
39	AGND1	P	Analog ground	
40	AVDD1	P	Analog Power	
41	VCOMin	I	For external VCOM DC input (Optional)	
42	DITH	I	Dithering setting DITH = "L" 6bit resolution(last 2 bits of input data turncated) DITH = "H" 8bit resolution(Default setting)	
43	NC	-	Not connect	
44	VCOM	O	connect a capacitor	
45	V10	P	Gamma correction voltage reference	
46	V9	P	Gamma correction voltage reference	
47	V8	P	Gamma correction voltage reference	
48	V7	P	Gamma correction voltage reference	
49	V6	P	Gamma correction voltage reference	
50	V5	P	Gamma correction voltage reference	
51	V4	P	Gamma correction voltage reference	
52	V3	P	Gamma correction voltage reference	
53	V2	P	Gamma correction voltage reference	
54	V1	P	Gamma correction voltage reference	
55	NC	-	Not connect	
56	VGH	P	Positive power for TFT	
57	GVCC	P	Digital Power	
58	VGL	P	Negative power for TFT	
59	GGND	P	Digital Ground	
60	CAP	C	Connected to a capacitor	

I: Input; P: Power; G: Ground; C: Capacitor

b. Backlight driving section (Refer to Figure 1)

No.	Symbol	I/O	Description	Remark
1	HI	I	Power supply for backlight unit (High voltage)	--
2	GND	-	Ground for backlight unit	--

## 2. Absolute maximum ratings

Item	Symbol	Condition	Min.	Max.	Unit	Remark
Power voltage	$V_{CC}$	GND=0	-0.5	5	V	
	$AV_{DD}$	$AV_{SS}=0$	-0.5	15	V	
	$V_{GH}$	GND=0	-0.3	42	V	
	$V_{GL}$		-20	0.3	V	
	$V_{GH}-V_{GL}$		-	40	V	
Input signal voltage	$V_I$		-0.3	$V_{CC}+0.3$	V	Note 1
	VCOM		0	6.5	V	
Operating temperature	Topa		-10	60	°C	
Storage temperature	Tstg		-20	70	°C	

Note 1: HS , VS , DE , Digital Data

## 3. Electrical characteristics

## a. Typical operating conditions (GND=AVSS=0V, Note 2)

Item	Symbol	Min.	Typ.	Max.	Unit	Remark	
Power supply	$V_{CC}$	2.7	3.3	3.6	V		
	$AV_{DD}$	11	12.5	14	V		
	$V_{GH}$	7	-	VEE+40	V		
	$V_{GL}$	-20	-	-5	V		
VCOM	$V_{CDC}$	TBD	TBD	TBD	V	DC component	
Input signal voltage	H Level	$V_{IH}$	$0.7 V_{CC}$	-	$V_{CC}$	V	Note 1
	L Level	$V_{IL}$	0	-	$0.3 V_{CC}$		
Input level of V1~V7	$V_x$	VCOMDC	-	$AV_{DD}-0.5$		Positive gamma correction voltage	
Input level of V8~V14	$V_x$	0.5	-	VCOMDC		Negative gamma correction voltage	

Note 1: HS , VS , DE, Digital Data

## b. DC/DC converters

Item	Symbol	Min.	Typ.	Max.	Unit	Remark
DRV output voltage	VDRV	0	VCC		V	
Feed back voltage	VFB	0.55	0.6	0.65	V	DC/DC converters. BL current = 150mA
Base drive current for PWM	IDRV		60		mA	DRV=0.7V
Duty cycle maximum	$\delta_{MAX}$			87.50%		

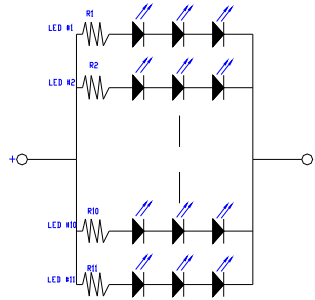


## c. Backlight driving conditions

Parameter	Symbol	Min.	Typ.	Max.	Unit	Remark
LED lightbar voltage	$V_L$	10	12	12	V	Note 1, 2
LED Lightbar current	$I_L$	-	160	-	mA	Note 1, 2
LED Lightbar life time		10,000	-	-	Hr	Note 1, 2, 3, 4

Note 1: LED backlight is LED lightbar type(24 pcs of LED).

Note 2: Definition of "LED Lifetime": brightness is decreased to 50% of the initial value. LED Lifetime is restricted under normal condition, ambient temperature = 25°C and LED lightbar voltage = 12V

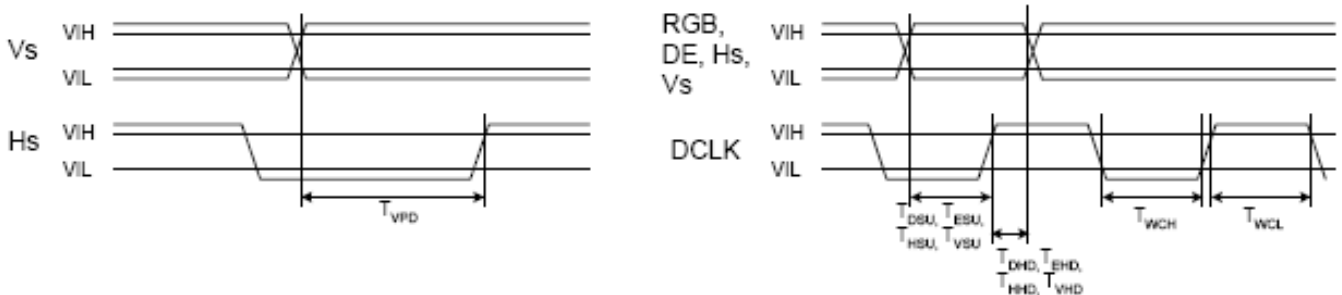


Note 3: The value is only for reference.

Note 4: If it operates with LED lightbar voltage more than 12V, it maybe decreases LED lifetime.

## 4. AC Timing

Parameter	Symbol	Min.	Typ.	Max.	Unit.	Remark
Clock High time	$T_{WCL}$	8	-	-	ns	
Clock Low time	$T_{WCH}$	8	-	-	ns	
Hsync setup time	$T_{HSU}$	5	-	-	ns	
Hsync hold time	$T_{HHD}$	10	-	-	ns	
Vsync setup time	$T_{VSU}$	0	-	-	ns	
Vsync hold time	$T_{VHD}$	2	-	-	ns	
Data setup time	$T_{DSU}$	5	-	-	ns	
Data hold time	$T_{DHD}$	10	-	-	ns	
Data enable set-up time	$T_{ESU}$	4	-	-	ns	
Data enable hold time	$T_{EHD}$	2	-	-	ns	

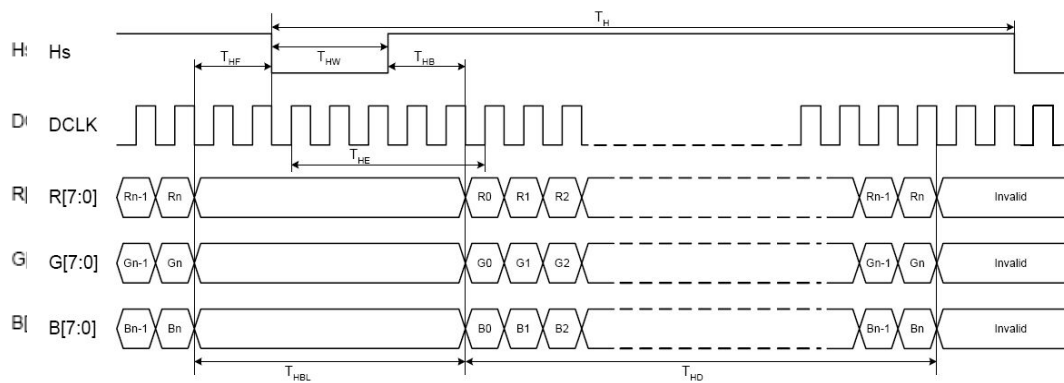


Input timing details

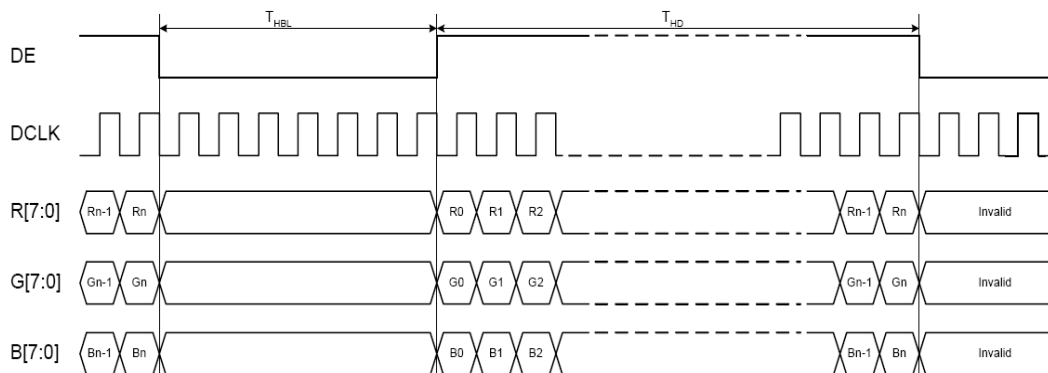
## 5. RGB Parallel Input Timing

## a. Horizontal timing

Parameter	Symbol	Min.	Typ.	Max.	Unit.	Remark
DCLK frequency	$F_{DCLK}$	25	33	40	MHz	
DCLK period	$T_{DCLK}$	25	30.3	40	ns	
Hsync period (= $T_{HD} + T_{HBL}$ )	$T_H$	986	1056	1183	DCLK	
Active Area	$T_{HD}$	-	800	-	DCLK	
Horizontal blanking (= $T_{HF} + T_{HE}$ )	$T_{HBL}$	186	256	383	DCLK	
Hsync front porch	$T_{HF}$	-	40	-	DCLK	
Delay from Hsync to 1 <sup>st</sup> data input (= $T_{HW} + T_{HB}$ )	$T_{HE}$	88	216	343	DCLK	Function of HDL[7..0] settings
Hsync pulse width	$T_{HW}$	1	128	136	DCLK	
Hsync back porch	$T_{HB}$	10	88	342	DCLK	



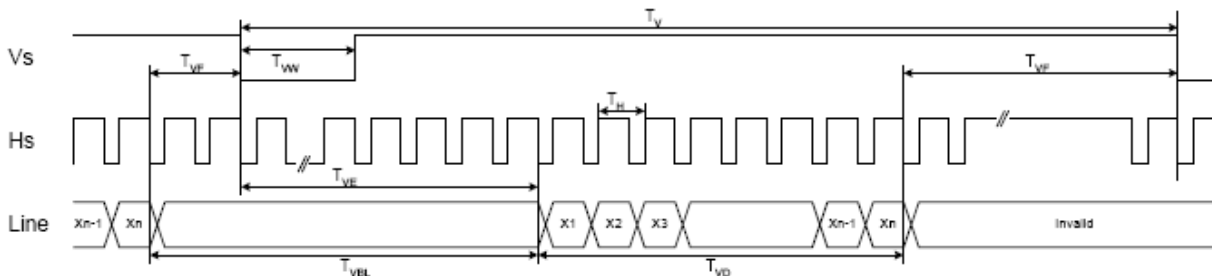
Horizontal input timing (HV mode)



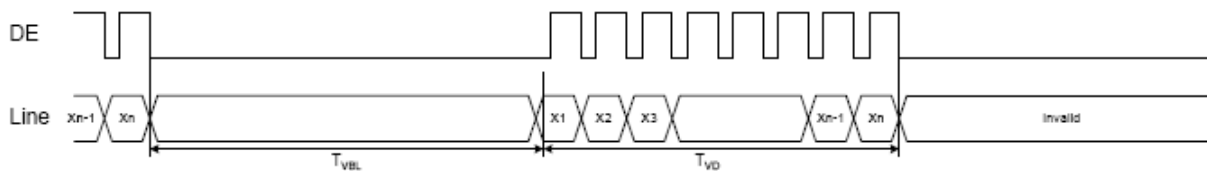
Horizontal input timing (DE mode)

## b. Vertical timing

Parameter	Symbol	Min.	Typ.	Max.	Unit.	Remark
Vsync period (= $T_{VD} + T_{VBL}$ )	$T_V$	620	628	635	Th	
Active lines	$T_{VD}$	-	600	-		
Vertical blanking (= $T_{VF} + T_{VE}$ )	$T_{VBL}$	20	28	35	Th	
Vsync front porch	$T_{VF}$	-	1	-	Th	
GD start pulse delay	$T_{VE}$	19	27	34	HS	Function of VDL[3..0] settings
Vsync pulse width	$T_{VW}$	1	3	16	Th	
Hsync/Vsync phase shift	$T_{VPD}$	2	320	-	DCLK	



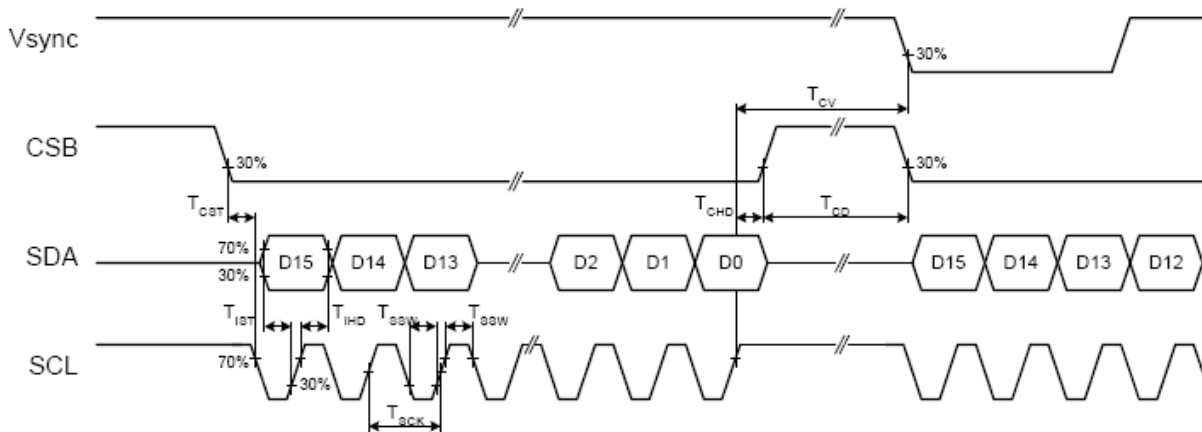
Vertical timing (HV mode)



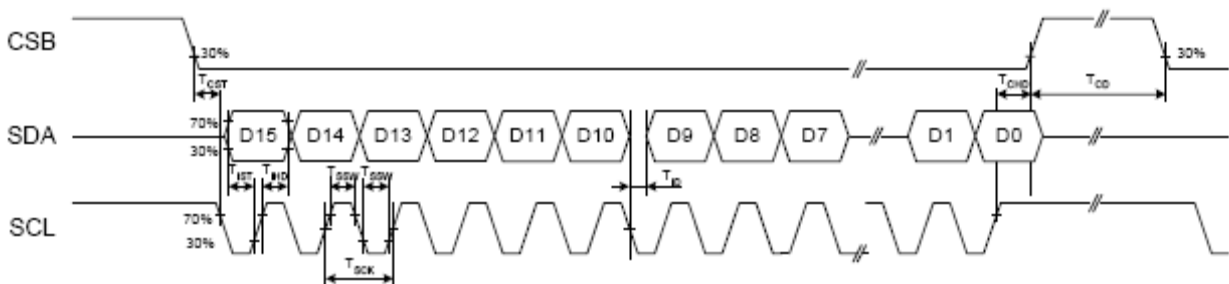
Vertical timing (DE mode)

## 6. Serial control interface

Parameter	Symbol	Min.	Typ.	Max.	Unit.	Remark
Serial data setup time	$T_{IST}$	120	-	-	ns	
Serial data hold time	$T_{IHD}$	120	-	-	ns	
CSB setup time	$T_{CST}$	120	-	-	ns	
CSB hold time	$T_{CHD}$	120	-	-	ns	
Serial clock high/low	$T_{SSW}$	120	-	-	ns	
Serial clock	$T_{SCK}$	320	-	-	ns	
Delay from CSB to VSYNC	$T_{CV}$	1	-	-	us	
Chip select distinguish	$T_{CD}$	1	-	-	us	
Serial data output delay	$T_{ID}$	-	-	60	ns	CL=20pF



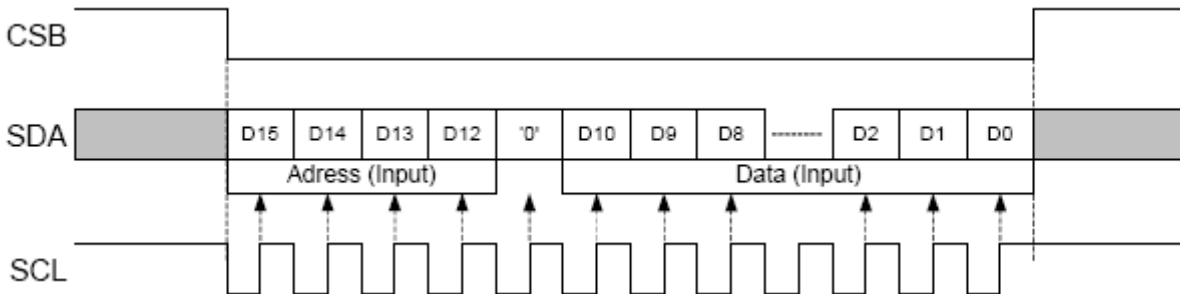
AC serial interface write mode timings



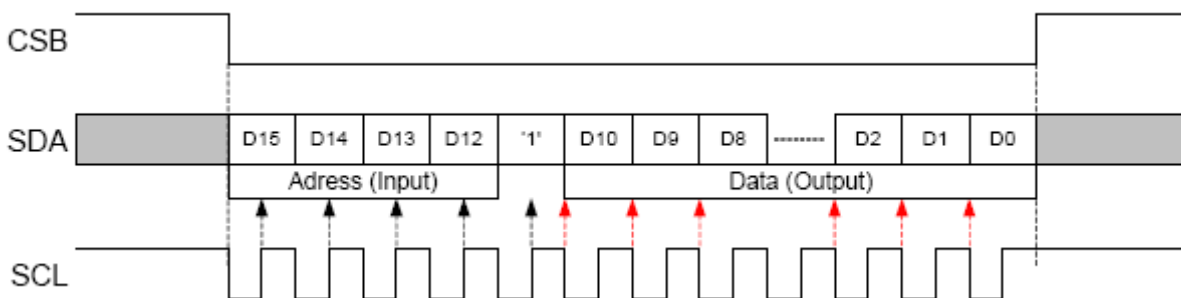
AC serial interface read mode timings

## 7. Register Bank

There is a total of 6 registers each containing several parameters. For a detailed description of the parameters refer to register table. The serial register has read/write function. D[15:12] are the register address, D[11] defines the read or write mode and D[10:0] are the data.



Serial Interface Write sequence



Serial Interface Read sequence

1. At power-on, the default values specified for each parameter are taken.
2. If less than 16-bit data are read during the CS low time period, the data is cancelled.
  - a. The write operation is cancelled.
  - b. The read operation is interrupt.
3. If more than 16-bit data are read during the CS low time period, the last 16 bits are kept.
  - a. Address & R/W are always defined from CSB falling edge.
  - b. The write operation load last 11 bit data before CSB rising edge.
  - c. The read operation is "D0" is output to SDA until CSB rising edge.
4. All items are set at the falling edge of the vertical sync, except R0[1:0].
5. When GRB is activated through the serial interface, all registers are cleared, except the GRB value.
6. Register R/W setting: D11 = "L" → write mode; D11 = "H" → read mode.
7. The register setting values are valid when VCC already goes to high and after VSYNC starts.
8. It is suggested that VSYNC, HSYNC, DCLK always exists in the same time. But if HSYNC, DCLK stops, only VSYNC operating, the register setting is still valid.
9. If the chip goes to standby mode, the register value will still keep. MCU can wake up the chip only by changing standby mode value from low to high.

10. The register setting values are rewritten by the influence of static electricity, a noise, etc. to unsuitable value, incorrect operating may occur. It is suggested that the SPI interface will setup as frequently as possible.

## 8. Serial Register table

Reg	ADDRESS				R/W	DATA											
	No.	D15	D14	D13		D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1
R0	0	0	0	0	R/W		1		1		DITH (1)	U/D (0)	SHL (1)	SHDB1 (1)	0	GRB (1)	STB (4)
R1	0	0	0	1	R/W	x	0	1	VCOM_M (10)			VCOM_LVL (2Fh)					
R2	0	0	1	0	R/W	x	x	x	HDL (80h)								
R3	0	0	1	1	R/W	x	x	x	x								
R6	0	1	1	0	R/W	x	EnGB13 (0)	EnGB12 (1)	EnGB11 (1)	EnGB10 (1)	EnGB9 (0)	EnGB6 (0)	EnGB5 (1)	EnGB4 (1)	EnGB3 (1)	EnGB2 (0)	
R15	1	1	1	1	R/W	x	x	x	x	x	x	x	x	x	x	1	1

X: Reserved. Please set to "0".

## 9. Register Description

### a. R0 setting

Address	Bit	Description	Default
0000	[10..0]	Bits 10-9	AUO Internal Use
		Bits7-8	AUO Internal Use
		Bit6 (DITH)	Dithering function.
		Bit5 (U/D)	Vertical shift direction selection.
		Bit4 (SHL)	Horizontal shift direction selection.
		Bit3 (SHDB1)	AVDD DC-DC converter shutdown setting.
		Bit2	AUO Internal Use
		Bit1 (GRB)	Global reset.
		Bit0 (STB)	Standby mode setting.

Bit6	DITH function
0	DITH off.
1	DITH on. <b>(default)</b>

Bit5	U/D function
0	Scan down; First line= Gn -> Gn-1 -> ... -> G2 -> Last line=G0. <b>(default)</b>
1	Scan up; First line= G0 -> G2 -> ... -> Gn-1 -> Last line=Gn

Bit4	SHL function
0	Shift left; First data= Y600 -> Y599 -> ... -> Y2 -> Last data=Y1.
1	Shift right; First data= Y1 -> Y2 -> ... -> Y599 -> Last data=Y600. <b>(default)</b>

Bit3	SHDB1 function
0	AVDD DC-DC converter is off.
1	AVDD DC-DC converter is on. <b>(default)</b>

Bit1	GRB function
0	The controller is reset. Reset all registers to default value.
1	Normal operation. <b>(default)</b>

Bit0	STB function
0	T-CON, source driver and DC-DCs converters are off. All outputs are set to GND.
1	Normal operation. <b>(default)</b>

#### b. R1 setting

Address	Bit	Description	Default
0001	[8..0]	Bit9-8	AUO Internal Use
		Bit7-6 (VCOM_M)	VCOM mode signal.
		Bit5-0 (VCOM_LVL)	VCOM level adjustment. Step 31.25mV/LSB @AVDD=12.5V (AVDD/400)

Bit7-6	VCOM_M function
00	VCOM generator disabled. VCOM is generated externally.
01	VOM internal reference disabled. DC voltage of VCOM follows VOMin signal. <b>(default)</b>
1x	VCOM generator enabled. DC voltage of VCOM follows VCOM_LVL settings.

Bit5-0	VCOM_LVL function @V1=12.5V
00h	$VCOM\_LVL = V1/2 - 47 * 31/25mV = 4.78125V$
01h	$VCOM\_LVL = V1/2 - 46 * 31/25mV = 4.8125V$
2Fh	$VCOM\_LVL = V1/2 = 6.25$ <b>(default)</b>
3Eh	$VCOM\_LVL = V1/2 + 15 * 31.25mV = 6.71875V$
3Fh	$VCOM\_LVL = V1/2 + 16 * 31.25mV = 6.75V$

#### c. R2 setting

Address	Bit	Description	Default
0010	[7..0]	Bit7-0(HDL)	Horizontal start pulse adjustment function

Bit7-0	HDL function
00h	$T_{HE} = T_{HEtyp} - 128 \text{ CLK period.}$
80h	$T_{HE} = T_{HEtyp}$ <b>(default)</b>
FFh	$T_{HE} = T_{HEtyp} + 127 \text{ CLK period.}$

## d. R3 setting

Address	Bit	Description		Default
0011	[6..0]	Bit6	AUO Internal Use	0
		Bit5	AUO Internal Use	0
		Bit4	AUO Internal Use	0
		Bit3-0(VDL)	Vertical start pulse adjustment function	

Bit3-0	VDL function
0000	$T_{VE} = T_{VEtyp} - 8$ Hs period.
0001	$T_{VE} = T_{VEtyp} - 7$ Hs period.
0010	$T_{VE} = T_{VEtyp} - 6$ Hs period.
0011	$T_{VE} = T_{VEtyp} - 5$ Hs period.
0100	$T_{VE} = T_{VEtyp} - 4$ Hs period.
0101	$T_{VE} = T_{VEtyp} - 3$ Hs period.
0110	$T_{VE} = T_{VEtyp} - 2$ Hs period.
0111	$T_{VE} = T_{VEtyp} - 1$ Hs period.
1000	$T_{VE} = T_{VEtyp}$ . (default)
1001	$T_{VE} = T_{VEtyp} - 1$ Hs period.
1010	$T_{VE} = T_{VEtyp} - 2$ Hs period.
1011	$T_{VE} = T_{VEtyp} - 3$ Hs period.
1100	$T_{VE} = T_{VEtyp} - 4$ Hs period.
1101	$T_{VE} = T_{VEtyp} - 5$ Hs period.
1110	$T_{VE} = T_{VEtyp} - 6$ Hs period.
1111	$T_{VE} = T_{VEtyp} - 7$ Hs period.

## e. R6 setting

Address	Bit	Description		Default
0110	[9..0]	Bits9(EnGB13)	Gamma buffer Enable for V13	01_1100
		Bits8(EnGB12)	Gamma buffer Enable for V12	_1110b
		Bits7(EnGB11)	Gamma buffer Enable for V11	
		Bits6(EnGB10)	Gamma buffer Enable for V10	
		Bits5(EnGB9)	Gamma buffer Enable for V9	
		Bits4(EnGB6)	Gamma buffer Enable for V6	
		Bits3(EnGB5)	Gamma buffer Enable for V5	
		Bits2(EnGB4)	Gamma buffer Enable for V4	
		Bits1(EnGB3)	Gamma buffer Enable for V3	
		Bits0(EnGB2)	Gamma buffer Enable for V2	

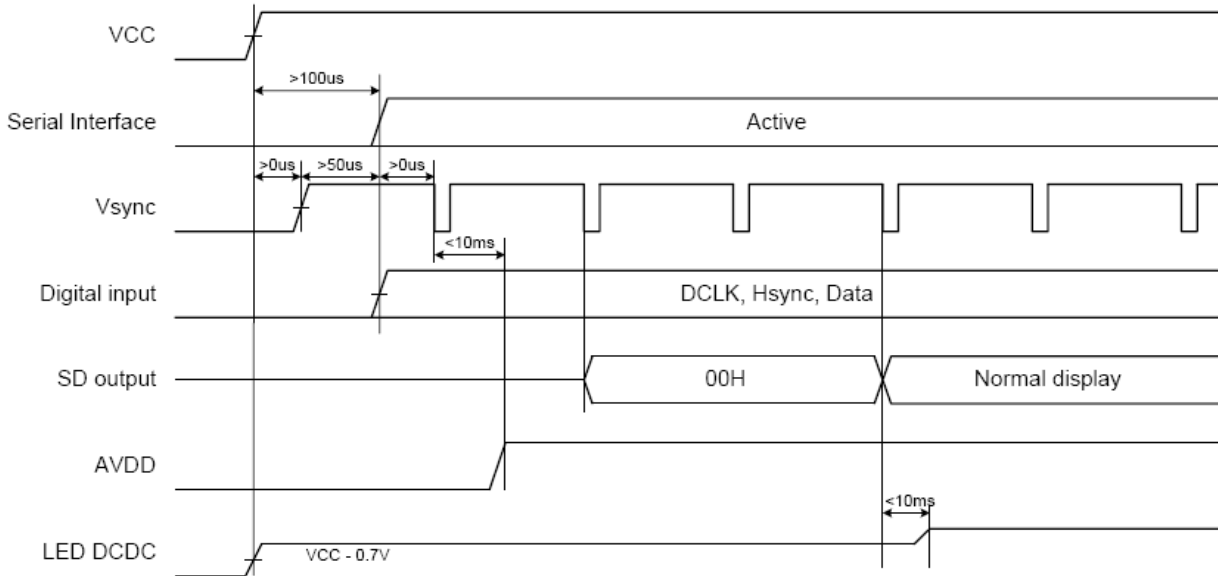
Bitx	EnGBx function
0	Gamma buffer for VX is disabled (High Z).
1	Gamma buffer is enabled. VX must be connected externally.



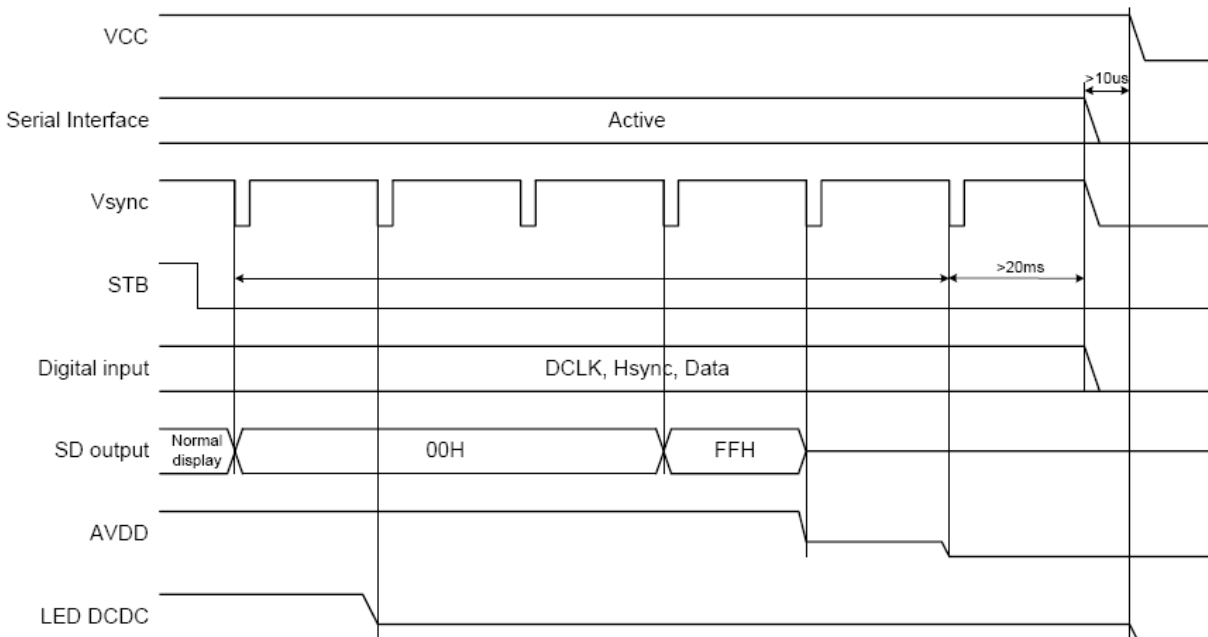
### 10. Power Sequence

Sequence for power on/off and Signal on/off

#### a. Power on sequence



#### b. Power off sequence



### C. Optical specification (Note 1, Note 2)

Item		Symbol	Condition	Min.	Typ.	Max.	Unit	Remark
Response time	Rise	Tr	$\theta = 0^\circ$	-	12	24	ms	Note 3,5
	Fall	Tf		-	18	36	ms	
Contrast ratio		CR	At optimized Viewing angle	300	400	-		Note 4, 5
Viewing angle	Top		$CR \geq 10$	40	50	-	deg.	Note 5, 6
	Bottom			55	65	-		
	Left			55	65	-		
	Right			55	65	-		
Brightness		$Y_L$	$V_L = 12V$	150	200	-	cd/m <sup>2</sup>	Note 7
White chromaticity		X	$\theta = 0^\circ$	TBD	TBD	TBD		Note 7
		Y	$\theta = 0^\circ$	TBD	TBD	TBD		

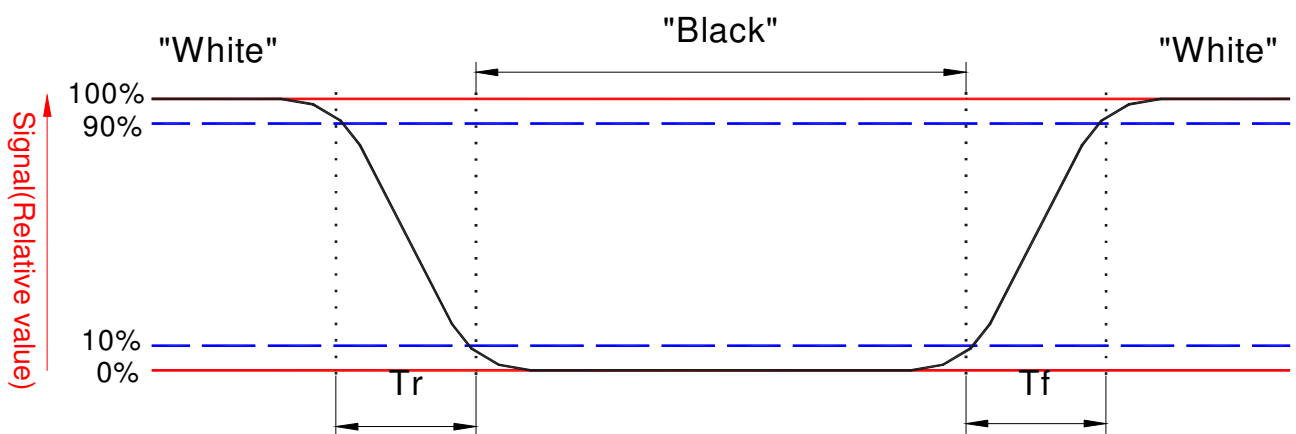
Note 1 : To be measured in the dark room. Ambient temperature =25°C , and LED lightbar voltage  $V_L = 12V$ .

Note 2 :To be measured on the center area of panel with a viewing cone of 1°by Topcon luminance meter BM-5A, after 15 minutes operation.

Note 3. Definition of response time:

The output signals of photo detector are measured when the input signals are changed from "black" to "white"(falling time) and from "white" to "black"(rising time), respectively.

The response time is defined as the time interval between the 10% and 90% of amplitudes. Refer to figure as below.



Note 4. Definition of contrast ratio:

Contrast ratio is calculated with the following formula.

$$\text{Contrast ratio (CR)} = \frac{\text{Photo detector output when LCD is at "White" state}}{\text{Photo detector output when LCD is at "Black" state}}$$

Note 5. White  $V_i = V_{i50} + 1.5V$

Black  $V_i = V_{i50} \pm 2.0V$

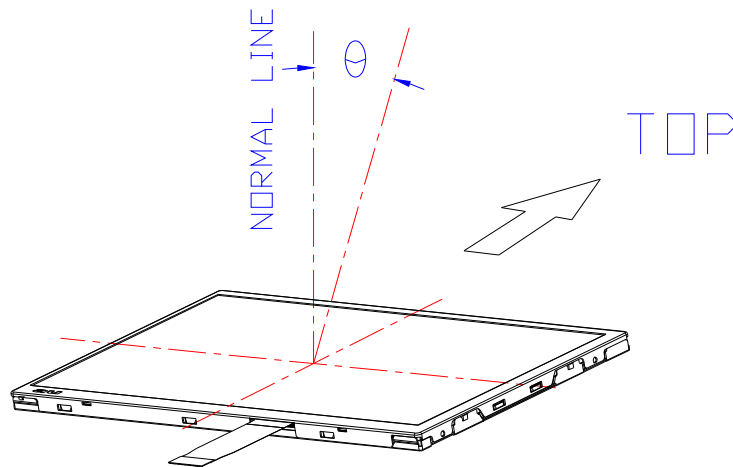
“±” means that the analog input signal swings in phase with  $V_{COM}$  signal.

“ $\bar{\pm}$ ” means that the analog input signal swings out of phase with  $V_{COM}$  signal.

$V_{i50}$  : The analog input voltage when transmission is 50%

The 100% transmission is defined as the transmission of LCD panel when all the input terminals of module are electrically opened.

Note 6. Definition of viewing angle, Refer to figure as below.



Note 7. Measured at the center area of the panel when all the input terminals of LCD panel are electrically opened.

**D. Reliability test conditions (Note 2):**

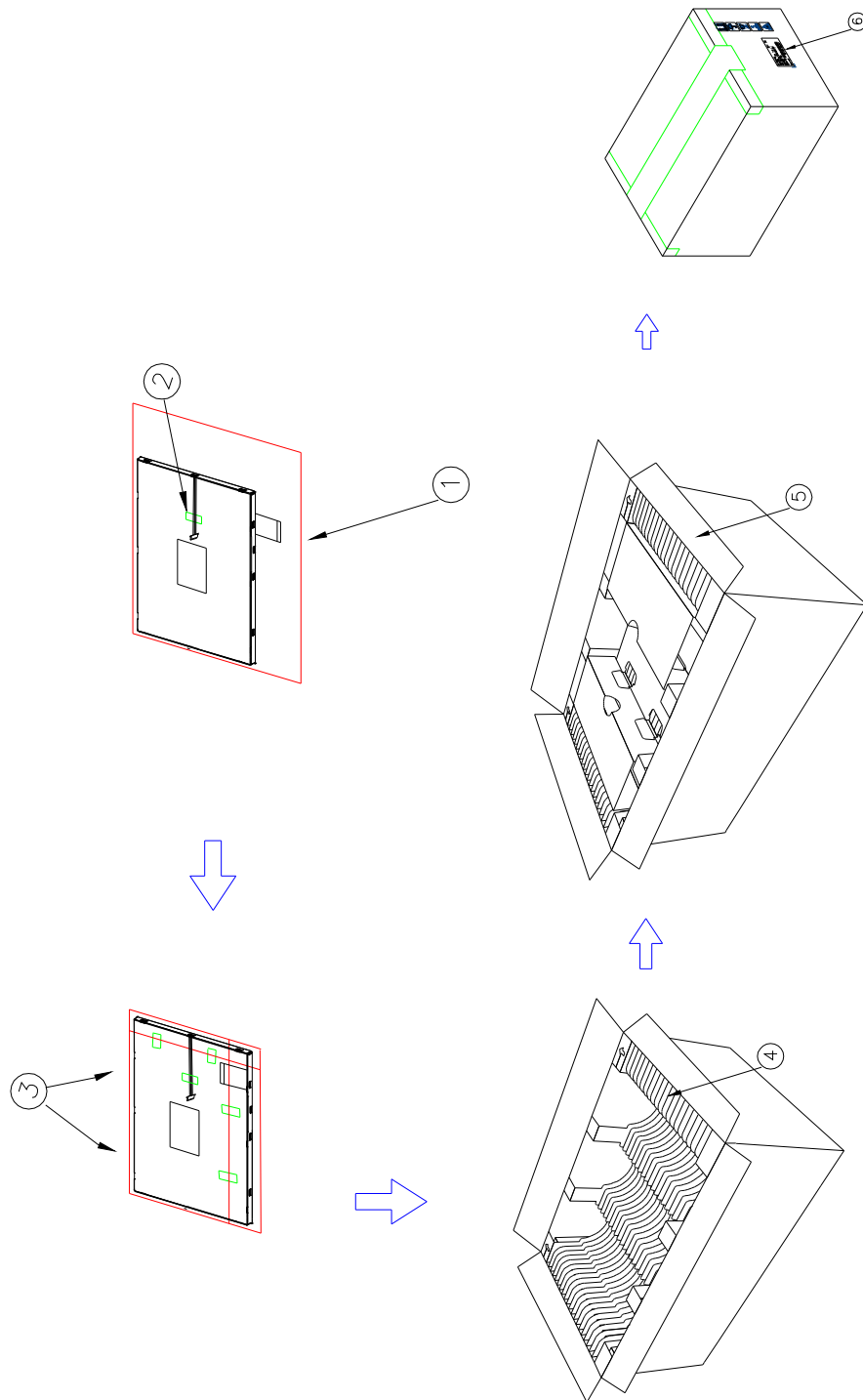
No.	Test items	Conditions	Remark
1	High temperature storage	Ta= 70℃                      240Hrs	
2	Low temperature storage	Ta= -20℃                      240Hrs	
3	High temperature operation	Tp= 60℃                      240Hrs	
4	Low temperature operation	Ta= -10℃                      240Hrs	
5	High temperature and high humidity	Tp= 50℃, 80% RH              240Hrs	Operation
6	Heat shock	-10℃~60℃/ 100 cycles 1Hrs/cycle	Non-operation
7	Electrostatic discharge	±200V,200pF(0Ω), once for each terminal	Non-operation
8	Vibration	Frequency range              : 10~55Hz Stoke                                : 1.5mm Sweep                               : 10 ~ 55 ~ 10Hz 2 hours for each direction of X,Y,Z (6 hours for total)	JIS C7021, A-10 Condition A
9	Mechanical shock	100G, 6ms, ±X,±Y,±Z 3 times for each direction	JIS C7021, A-7 Condition C
10	Vibration (with carton)	Random vibration: 0.015G <sup>2</sup> /Hz from 5~200Hz -6dB/octave from 200~500Hz	IEC 68-34
11	Drop (with carton)	Height: 60cm 1 corner, 3 edges, 6 surfaces	JIS Z0202

Note1: Ta: Ambient Temperature.

Note2: Tp: Panel Surface Temperature

Note3: In the standard conditions, there is not display function NG issue occurred. All the cosmetic specification is judged before the reliability stress.

### E. Packing form



Max. capacity: 30 modules  
Max. Weight : 7kg  
Carton outline : 520 x 340 x 250 mm



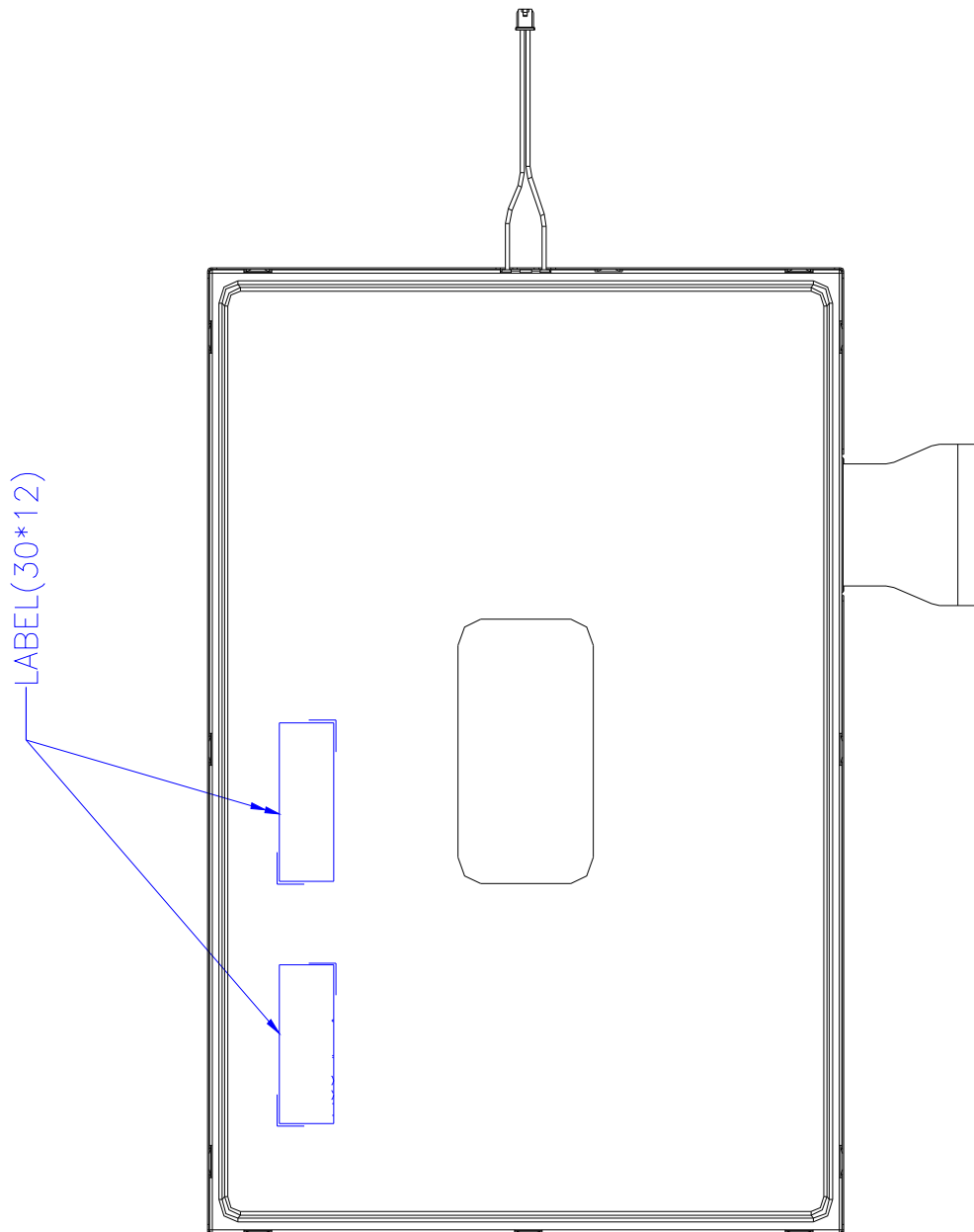


Fig.1-(b) Outline dimension of TFT-LCD module(Back side)